



### 3.3V Low Skew 1-to-4 LVTTL/LVCMOS to LVDS Fanout Buffer

### **Features**

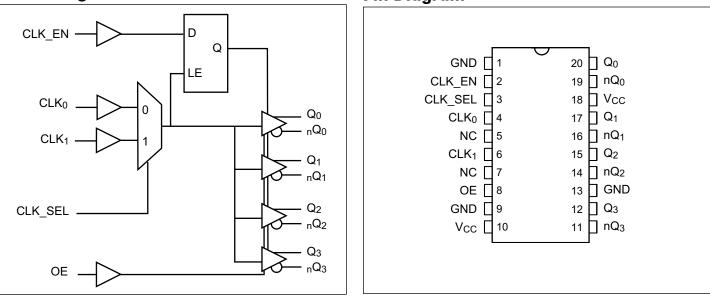
- → Maximum operation frequency: 650 MHz
- → 4 pair of differential LVDS outputs
- $\rightarrow$  Selectable CLK<sub>0</sub> and CLK<sub>1</sub> inputs
- → CLK<sub>0</sub>, CLK<sub>1</sub> accept LVCMOS, LVTTL input level
- → Output Skew: 40ps (maximum)
- → Part-to-part skew: 300ps (maximum)
- → Propagation delay: 2.2ns (maximum)
- $\rightarrow$  3.3V power supply
- → Pin-to-pin compatible to ICS8545
- $\rightarrow$  Operating Temperature: -40°C to 85°C
- → Packaging (Pb-free & Green): - 20-pin TSSOP (L)

### **Block Diagram**

## Description

The PI6C48545 is a high-performance low-skew LVDS fanout buffer. PI6C48545 features two selectable single-ended clock inputs and translate to four LVDS outputs. The CLK<sub>0</sub> and CLK<sub>1</sub> inputs accept LVCMOS or LVTTL signals. The outputs are synchronized with input clock during asynchronous assertion/deassertion of CLK\_EN pin. PI6C48545 is ideal for single-ended LVTTL/LVCMOS to LVDS translations. Typical clock translation and distribution applications are data-communications and telecommunications.

### Pin Diagram







# **Pin Description**

Name	Pin #	Туре	Description	
GND	1, 9, 13	Р	Connect to Ground	
CLK_EN	2	I_PU	Synchronizing clock enable. When high, clock outputs follow clock input. When low, Qx outputs are forced low, nQx outputs are forced high. LVCMOS/LVTTL level with $80k\Omega$ pull up.	
CLK_SEL	3	I_PD	Clock select input. When high, selects $CLK_1$ input. When low, selects $CLK_0$ input. LVCMOS/LVTTL level with $80k\Omega$ pull down.	
CLK <sub>0</sub>	4	I_PD	VCMOS / LVTTL clock input	
CLK <sub>1</sub>	6	I_PD	LVCMOS / LVTTL clock input	
NC	5,7		No internal connection.	
OE	8	I_PU	Output Enable. Controls outputs Q <sub>0</sub> , nQ <sub>0</sub> through Q <sub>3</sub> , nQ <sub>3</sub> .	
V <sub>CC</sub>	10, 18	Р	Connect to 3.3V.	
Q3, nQ3	12, 11	0	Differential output pair, LVDS interface level.	
Q <sub>2</sub> , <sub>n</sub> Q <sub>2</sub>	15, 14	0	Differential output pair, LVDS interface level.	
$Q_1, nQ_1$	17, 16	0	Differential output pair, LVDS interface level.	
Q <sub>0</sub> , <sub>n</sub> Q <sub>0</sub>	20, 19	0	Differential output pair, LVDS interface level.	

Notes:

1. I = Input, O = Output, P = Power supply connection, I\_PD = Input with pull down, I\_PU = Input with pull up.

### **Pin Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
C <sub>IN</sub>	Input Capacitance			6		pF
R_pullup	Input Pullup Resistance			80		1-0
R_pulldown	Input Pulldown Resistance			80		kΩ

# **Control Input Function Table**

		Inputs	Out	puts	
OE	CLK_EN	CLK_SEL	Selected Source	Q0:Q3	nQ0:nQ3
1	0	0	CLK0	Diasbled: Low	Diasbled: High
1	0	1	CLK1	Disabled: Low	Disabled: High
1	1	0	CLK0	Enabled	Enabled
1	1	1	CLK1	Enabled	Enabled
0	x	х		HiZ	HiZ

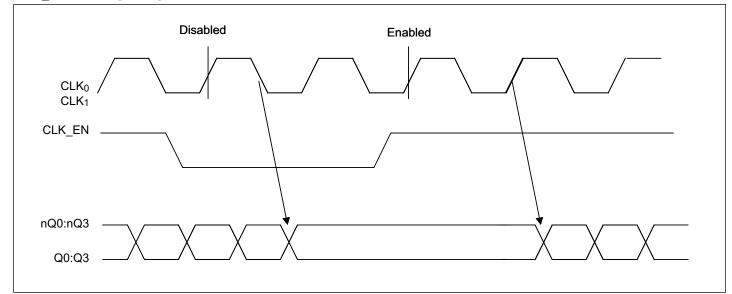
Notes:

1. After CLK\_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as show below.





### **CLK\_EN Timing Diagram**



# **Clock Input Function Table**

Inputs	Outputs		
CLK <sub>0</sub> or CLK <sub>1</sub>	Q0:Q3	nQ0:nQ3	
0	LOW	HIGH	
1	HIGH	LOW	





# **Absolute Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>CC</sub>	Supply voltage	Referenced to GND			4.6	
V <sub>IN</sub>	Input voltage	Referenced to GND	-0.5		V <sub>CC</sub> +0.5V	V
V <sub>OUT</sub>	Output voltage	Referenced to GND	-0.5		V <sub>CC</sub> +0.5V	
T <sub>STG</sub>	Storage temperature		-65		150	°C

#### Notes:

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only and 1. correct functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

### **Operating Conditions**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>CC</sub>	Power Supply Voltage		3.135	3.3	3.465	V
T <sub>A</sub>	Ambient Temperature		-40		85	°C
I <sub>CC</sub>	Power Supply Current				60	mA

### **LVCMOS/LVTTL DC Characteristics** ( $T_A = -40^{\circ}$ C to 85°C, $V_{CC} = 3.135$ V to 3.465V unless otherwise stated below.)

Symbol		Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>IH</sub>	Input High Voltage	CLK <sub>0</sub> , CLK <sub>1</sub> , CLK_EN, CLK_SE, OE		2		V <sub>CC</sub> +0.3	V
V	Input Low	CLK <sub>0</sub> , CLK <sub>1</sub>		-0.3		1.3	V
V <sub>IL</sub>	Voltage	CLK_EN, CLK_SEL, OE		-0.3		0.8	V
т	Input High	CLK0, CLK1, CLK_SEL	$V_{IN} = V_{CC} = 3.465 V$			150	uA
I <sub>IH</sub>	Current	CLK_EN, OE	$V_{IN} = V_{CC} = 3.465 V$			5	uA
I.,	Input Low	CLK <sub>0</sub> , CLK <sub>1</sub> , CLK_SEL	$V_{\rm IN} = 0V, V_{\rm CC} = 3.465V$	-5			uA
I <sub>IL</sub>	Current	CLK_EN, OE	$V_{\rm IN} = 0V, V_{\rm CC} = 3.465V$	-150			uA

### **LVDS DC Characteristics** ( $T_A = -40^{\circ}C$ to $85^{\circ}C$ , $V_{CC} = 3.135V$ to 3.465V unless otherwise stated below.)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>OD</sub>	Differential Output Voltage		200	280	360	mV
$\Delta V_{OD}$	V <sub>OD</sub> Magnitude Change			0	40	
V <sub>OS</sub>	Offset Voltage		1.125	1.3	1.475	V
$\Delta V_{OS}$	V <sub>OS</sub> Magnitude Change			5	25	mV
I <sub>OZ</sub>	High Impedance Leakage Current		-10		+10	۸
I <sub>OFF</sub>	Power OFF Leakage		-20	±1	+20	μA
I <sub>OSD</sub>	Differential Output Short Circuit Current			-3.5	-5	mA
I <sub>OS</sub>	Output Short Circuit Current			-3.5	-5	IIIA
V <sub>OH</sub>	Output Voltage High			1.34	1.6	V
V <sub>OL</sub>	Output Voltage Low		0.9	1.06		v





### AC Characteristics ( $T_A = -40^{\circ}$ C to $85^{\circ}$ C, $V_{CC} = 3.135$ V to 3.465V)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
f <sub>max</sub>	Output Frequency				650	MHz
t <sub>Pd</sub>	Propagation Delay <sup>(1)</sup>		0.8		2.2	ns
T <sub>sk(o)</sub>	Output-to-output Skew <sup>(2)</sup>				40	
T <sub>sk(pp)</sub>	Part-to-part Skew <sup>(3)</sup>				300	ps
t <sub>r</sub> /t <sub>f</sub>	Output Rise/Fall time	20% - 80%	100		300	
odc	Output duty cycle		48		52	%

Notes:

Measured from the  $V_{CC}/2$  of the input to the differential output crossing point 1.

2. Defined as skew between outputs at the same supply voltage and with equal load condition. Measured at the outputs differential crossing point.

3. Defined as skew between outputs on different parts operating at the same supply voltage and with equal load condition. Measured at the outputs differential crossing point.

All parameters are measured at 500MHz unless noted otherwise 4.

## **Part Marking**

L Package

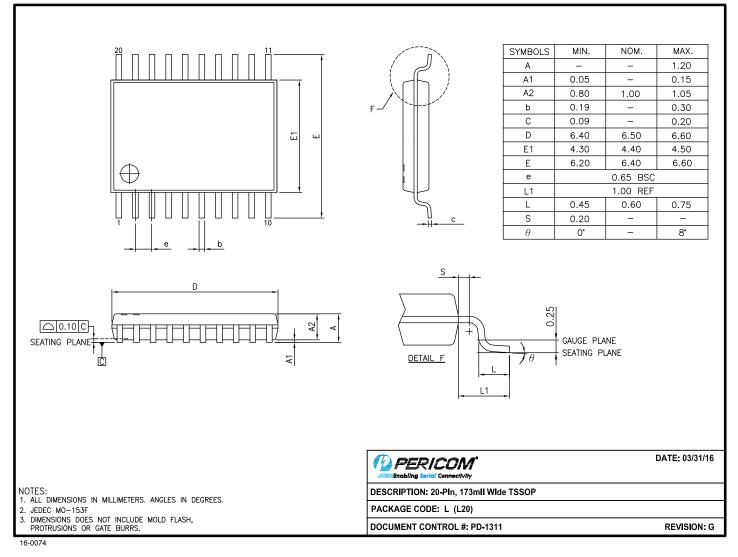


C: Die Rev YY: Year WW: Workweek 1st X: Assembly Code 2nd X: Fab Code





# Packaging Mechanical: 20-TSSOP (L)



### For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

# **Ordering Information**

Ordering Code	Package Code	Package Description
PI6C48545LEX	L	20-pin, 173-mil Wide (TSSOP)

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/

3. E = Pb-free and Green

4. X suffix = Tape/Reel





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